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Specification						
Part						
Number:	MCOB21205AV-EYP					
Version:						
Date:						

design • manufacture • supply

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1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2011/01/13 2011/07/02 2012/11/16	1 2 3	9	First release Change version Add CIE chromaticity diagram Modify CIE
2014/1/26	4		Update Rev.

2. General Specification

The Features is described as follow:

- Module dimension: 55.7 x 32.0 x 11.0 (max.) mm
- View area: 46.0 x 14.5 mm
- Active area: 38.95 x 11.80 mm
- Number of Characters: 12 Characters x 2 Line
- Dot size: 0.45 x 0.6 mm
- Dot pitch: 0.55x 0.70 mm
- Character size: 2.65 x 5.5 mm
- Character pitch: 3.6 x 6.3 mm
- Duty: 1/16
- Emitting Color: OLED , Yellow

Midas Displays OLED Part Number System

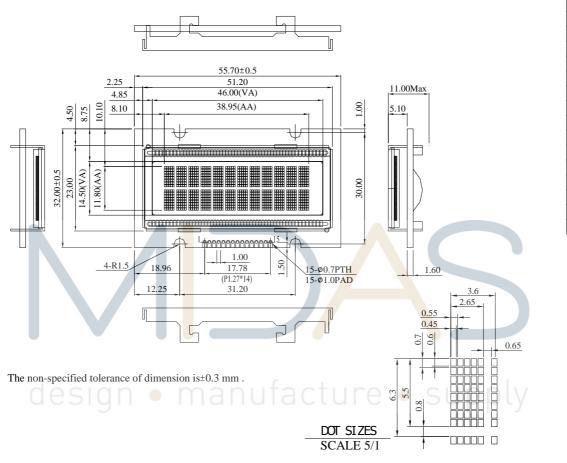
MC 1	_	B 216 2 3		* 5	V 6	-	Е 7	W 8	I 9	* 10
1	=	MCO:	Midas Dis	splays OLEI	D					
2	=	Blank:	B : COB (Chip on Boa	ard) T : TAE	3 (Taped Aut	omated Bo	onding)		
3	=	No of dots:	(e.g. 2400	064 = 240 x	64 dots)	(e.g. 2160	5 = 2 x 16	5mm C.H.))	
4	=	Series	A to Z							
5	=	Series Variant:	A to Z and	d 1 to 9 – se	ee addendur	n				
6	=	Operating Temp	Range: A: -30+8 X: -40 +8		-40+80° C	Y: -40 +70)°C Z :	-30+70° C		
7	=	Character Set:		ot Applicable European Fo	e ont Set (Engli	sh/Japanese	e – Wester	n European	ı (K) – Cyri	illic (R))
8	=	Colour:	Y: Yellow	W: White	e B: Blue	R: Red	G: Green	RGB: Fu	ll Colour	
9	=	Interface:	P: Paralle	el I: l'	²C	S: SPI	М	: Multi		
10	=	Voltage Variant	e.g. 3 = 3	V						

F/Displays/Midas Brand/Midas NEW OLED Part Number System 18 June 2013 2011.doc

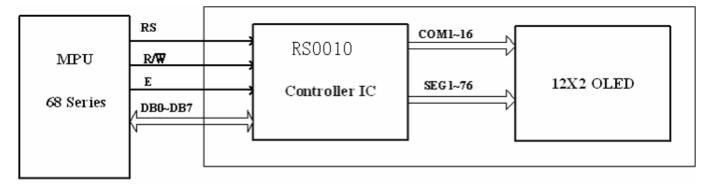
4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	VSS	0V	Ground
2	VDD	5.0V	Supply Voltage for logic
3	NC	_	
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read (Module> MPU) L: Write(MPU> Module)
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bit 0
8	DB1	H/L	Data bit 1
9	DB2	H/L	Data bit 2
10	DB3	H/L	Data bit 3
11	DB4	H/L	Data bit 4
12	DB5	H/L	Data bit 5
13	DB6	H/L	Data bit 6
14	DB7	H/L	Data bit 7
15	NC	_	
	des	ign 🔸	manutacture • supply

5. Outline Dimension



PIN NO.	SYMBOL
1	Vss
2	Vdd
3	NC
4	RS
5	R/W
6	Е
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	NC



/	Address	s Forma	at	DE	37	DE	36	DE	35	DE	34	DE	33	DE	32	DB1	DB0
CA	(Chara	icter Ad	dress)		1	ADI	D6	AD	D5	AD	D4	AD	D3	ADI	D2	ADD1	ADD0
1	2	3	4	 			9)	1	0	1	1	1	2			
CA1000000	CA10000001	CA10000010	CA10000011	 							CA10001010		C & 10001011				
CA11000000	CA11000001	CA11000010	CA11000011	 			0011001000		0.011001001		0.01001010		0.011001011				
	C	esi	gn	m	З	n	UŤ	а	C	t U	re	9		S			

6. Absolute Maximum Ratings

Item	Symbol	Min	Max	Unit	Notes
Operating Temperature	T _{OP}	-40	+80	°C	
Storage Temperature	T _{ST}	-40	+80	°C	
Supply Voltage For Logic	VDD-V _{SS}	-0.3	5.3	V	

7. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	VDD-VSS		4.8	5.0	5.3	V
Input High Volt.	VIH		0.8 VDD		VDD	V
Input Low Volt.	VIL	-	GND	-	0.2 VDD	V
Output High Volt.	VOH	IOH=-0.5mA	0.8 VDD		VDD	V
Output Low Volt.	VOL	IOL=0.5mA	GND		0.2 VDD	V
50% Check Board	IDD	VDD=5V	28	30	38	mA

Note: In order to avoid any possible damages, 3V or 3.3V logic I/O for VDD 5V OLED module is not recommended.

8. Optical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ		160			deg
view, aigio	(H)φ		160			deg
Contrast Ratio	CR	Dark	2000:1		_	
Response Time	T rise			10		μs
ntesponse nine	T fall			10		μs
Display with 50% check	Board Brightness		100	120		cd/m2
CIEx(Yellow)		(CIE1931)	0.45	0.47	0.49	
CIEy(Yellow)		(CIE1931)	0.48	0.50	0.52	
					5	



9. OLED Lifetime

ITEM	Conditions	Min	Тур	Remark
Operating Life Time	Ta=25℃ / Initial 50% check Board Typical Brightness Value	80,000 Hrs	100,000 Hrs	Note

Note:

- 1. Life time is defined the amount of time when the luminance has decayed to <50% of the initial value.
- 2. This analysis method uses life data obtained under accelerated conditions to extrapolate an estimated probability density function (*pdf*) for the product under normal use conditions.
- 3. Screen saving mode will extend OLED lifetime.



10. Reliability

Content of Reliability Test

Environmenta	I Test		
Test Item	Content of Test	Test Condition	Applicable Standard
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 240hrs	
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	80℃ 240hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-40°C 240hrs	
High Temperature/ Humidity Storage	Endurance test applying the high temperature and high humidity storage for a long time.	60°C ,90%RH 240hrs	
Temperature Cycle	Endurance test applying the low and high temperature cycle. -40°C25°C80°C 30min 5min 30min 1 cycle	-40℃/80℃ 100 cycles	
Mechanical Te	st		
Vibration test	Endurance test applying the vibration during transportation and using.	10~22Hz→1.5mmp-p 22~500Hz→1.5G Total 0.5hr	sup <u>p</u> ly
Shock test	Constructional and mechanical endurance test applying the shock during transportation.	50G Half sin wave 11 ms 3 times of each direction	
Atmospheric pressure test	Endurance test applying the atmospheric pressure during transportation by air.	115mbar 40hrs	
Others	· · · · · · · · · · · · · · · · · · ·	·	·
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

*Supply voltage for OLED module =Operating voltage at 25° C

Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability.
- 2. After the completion of the described reliability test, the samples were left at room temperature for 2 hrs prior to conducting the failure test at 23±5℃; 55±15% RH.
- 3. All-pixels-on is used as operation test pattern.
- 4. The degradation of Polarizer are ignored for High Temperature storage, High Temperature/ Humidity Storage, Temperature Cycle

Evaluation criteria

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within \pm 50% of initial value.

APPENDIX:

RESIDUE IMAGE

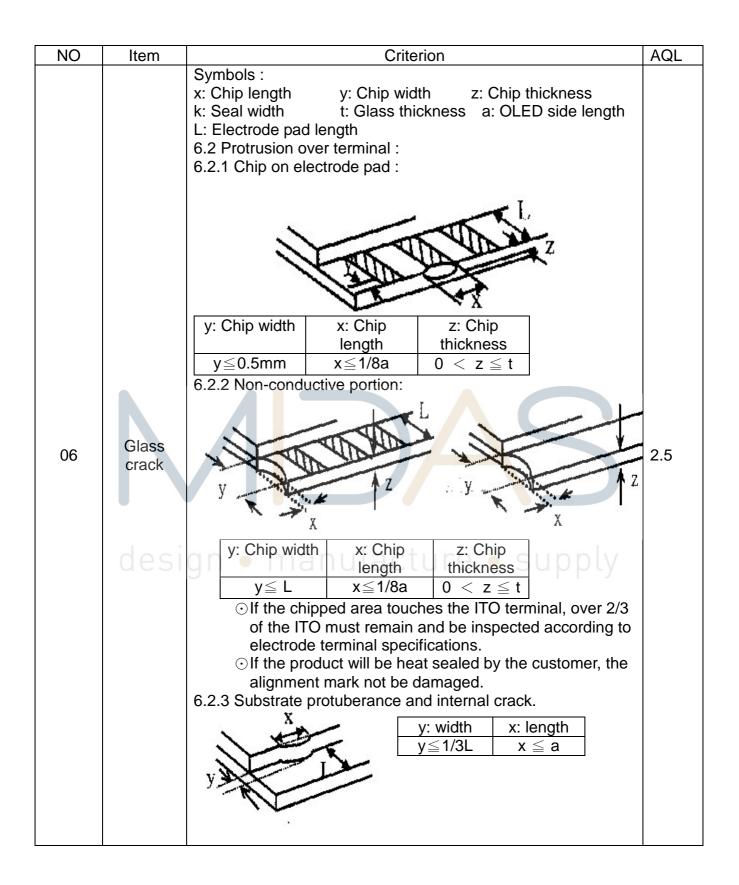
Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.

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11. Inspection specification

NO	Item	Criterion			AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 			0.65
02	Black or bright spots on OLED (display only)	 2.1 Bright and black spots on display ≤0.25mm, no more than three Bright or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 			2.5
03	Black spots, bright spots, contaminatio n	3.1 Round type : As following dr Φ=(x + y) / 2	awing	S	2.5
	(non-display)	→ <u>L</u> ← <u>L≦2.5</u>	wing) Width W≦0.02 0.02 < W≦0.03 0.03 < W≦0.05 0.05 < W	Acceptable Q TY Accept no dense	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.	Size Φ Φ \leq 0.20 0.20<Φ \leq 0.50 0.50<Φ \leq 1.00 1.00<Φ	Acceptable Q TY Accept no dense 3 2 0 3	2.5

NO	Item	Criterion		
05	Scratche s	Follow NO.3 black spots, bright spots, contamination		
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: OLED side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels: Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thickness Image: Chip of thi	2.5	
		viewing area		
		$\begin{tabular}{ c c c c c } \hline 1/2t < z \leq 2t & Not exceed & x \leq 1/8a \\ \hline 1/3k & & & \\ \hline \end{array}$		
	\odot If there are 2 or more chips, x is the total length of each			
l		chip.		



NO	Item	Criterion	AQL
07	Cracked	The OLED with extensive crack is not acceptable.	2.5
08	Bezel	8.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.8.2 Bezel must comply with job specifications.	2.5 0.65
9	PCB COB	 9.1 COB seal may not have pinholes larger than 0.2mm or contamination. 9.2 COB seal surface may not have pinholes through to the IC. 9.3 The height of the COB should not exceed the height indicated in the assembly diagram. 9.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 9.5 No oxidation or contamination PCB terminals. 9.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 9.7 The jumper on the PCB should conform to the product characteristic chart. 9.8 If solder gets on bezel tab pads, zebra pad or screw hold pad, make sure it is smoothed down. 9.9 The Scraping testing standard for Copper Coating of PCB 	 2.5 2.5 0.65 2.5 0.65 0.65 2.5 2.5 2.5
10	Soldering	 10.1 No un-melted solder paste may be present on the PCB. 10.2 No cold solder joints, missing solder connections, oxidation or icicle. 10.3 No residue or solder balls on PCB. 10.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
NO 11	Item General appearance	 Criterion 11.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 11.2 No cracks on interface pin (OLB) of TCP. 11.3 No contamination, solder residue or solder balls on product. 11.4 The IC on the TCP may not be damaged, circuits. 11.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 11.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 11.7 Sealant on top of the ITO circuit has not hardened. 11.8 Pin type must match type in specification sheet. 11.9 OLED pin loose or missing pins. 11.10 Product packaging must the same as specified on packaging specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65
	N	11.11 Product dimension and structure must conform to product specification sheet.	0.65

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Standard :

Check Item	Classification	Criteria
No Display	Major	
Missing Line	Major	
Pixel Short	Major	
Darker Short	Manufactu Major	
Wrong Display	Major	
Un-uniform B/A x 100% < 70% A/C x 100% < 70%	Major	
		A Normal B Dark Pixel C Light Pixel

12. Precautions in use of Modules

- (1) Avoid applying excessive shocks to module or making any alterations or modifications to it.
- (2) Don't make extra holes on the printed circuit board, modify its shape or change the components of OLED display module.
- (3) Don't disassemble the OLED display module.
- (4) Don't operate it above the absolute maximum rating.
- (5) Don't drop, bend or twist OLED display module.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) It's pretty common to use "Screen Saver" to extend the lifetime and Don't use fix information for long time in real application.
- (9) Don't use fixed information in OLED panel for long time, that will extend "screen burn" effect time..
- (10) T aa has the right to change the passive components, including R2and R3 adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (11) T a management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, T a make have the right to modify the version.)

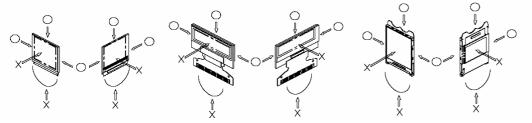
12.1 Handling Precautions

- (1) Since the display panel is being made of glass, do not apply mechanical impacts such us dropping from a high position.
- (2) If the display panel is broken by some accident and the internal organic substance leaks out, be careful not to inhale nor lick the organic substance.
- (3) If pressure is applied to the display surface or its neighborhood of the OLED display module, the cell structure may be damaged and be careful not to apply pressure to these sections.
- (4) The polarizer covering the surface of the OLED display module is soft and easily scratched. Please be careful when handling the OLED display module.
- (5) When the surface of the polarizer of the OLED display module has soil, clean the surface. It takes advantage of by using following adhesion tape.
- * Scotch Mending Tape No. 810 or an equivalent

Never try to breathe upon the soiled surface nor wipe the surface using cloth containing solvent Also, pay attention that the following liquid and solvent may spoil the polarizer:

- * Water
- * Ketone
- * Aromatic Solvents

(6) Hold OLED display module very carefully when placing OLED display module into the System housing. Do not apply excessive stress or pressure to OLED display module. And, do not over bend the film with electrode pattern layouts. These stresses will influence the display performance. Also, secure sufficient rigidity for the outer cases.



- (7) Do not apply stress to the LSI chips and the surrounding molded sections.
- (8) Do not disassemble nor modify the OLED display module.
- (9) Do not apply input signals while the logic power is off.
- (10) Pay sufficient attention to the working environments when handing OLED display modules to prevent occurrence of element breakage accidents by static electricity.
- * Be sure to make human body grounding when handling OLED display modules.
- * Be sure to ground tools to use or assembly such as soldering irons.
- * To suppress generation of static electricity, avoid carrying out assembly work under dry environments.
- * Protective film is being applied to the surface of the display panel of the OLED display module. Be careful since static electricity may be generated when exfoliating the protective film.
- (11) Protection film is being applied to the surface of the display panel and removes the protection film before assembling it. At this time, if the OLED display module has been stored surface of the display panel after removed of the film. In such case, remove the residue material by the method introduced in the above Section 5.
- (12) If electric current is applied when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful to avoid the above.

12.2 Storage Precautions

- (1) When storing OLED display modules, put them in static electricity preventive bags avoiding exposure to direct sun light nor to lights of fluorescent lamps. And, also, avoiding high temperature and high humidity environment or low temperature (less than 0℃) environments.(We recommend you to store these modules in the packaged state when they were shipped from T aaæ ÈAt that time, be careful not to let water drops adhere to the packages or bags nor let dewing occur with them.
- (2) If electric current is applied when water drops are adhering to the surface of the OLED display module, when the OLED display module is being dewed or when it is placed under high humidity environments, the electrodes may be corroded and be careful about the above.

12.3 Designing Precautions

- (1) The absolute maximum ratings are the ratings which cannot be exceeded for OLED display module, and if these values are exceeded, panel damage may be happen.
- (2) To prevent occurrence of malfunctioning by noise, pay attention to satisfy the VIL and VIH specifications and, at the same time, to make the signal line cable as short as possible.
- (3) We recommend you to install excess current preventive unit (fuses, etc.) to the power circuit (VDD). (Recommend value: 0.5A)

(4) Pay sufficient attention to avoid occurrence of mutual noise interference with the neighboring devices.

- (5) As for EMI, take necessary measures on the equipment side basically.
- (6) When fastening the OLED display module, fasten the external plastic housing section.
- (7) If power supply to the OLED display module is forcibly shut down by such errors as taking out the main battery while the OLED display panel is in operation, we cannot guarantee the quality of this OLED display module. Connection (contact) to any other potential than the above may lead to rupture of the IC.